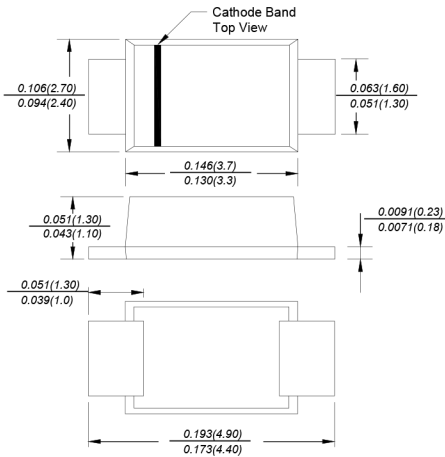


SMAF



FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Glass passivated chip junction

MECHANICAL DATA

Case: JEDEC SMAF molded plastic body over passivated chip
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.0018 ounce, 0.064 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

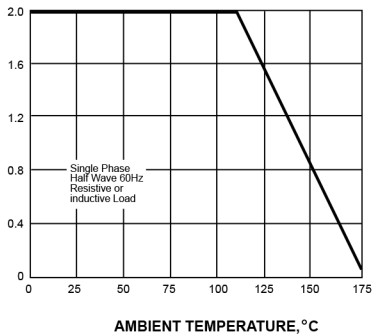
| TWGMC Catalog Number | SYMBOLS | S2AF | S2BF | S2DF | S2GF | S2JF | S2KF | S2MF | UNITS |
|---|-----------------|-------------|------|------|------|------|------|------|---------------------------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | VOLTS |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | VOLTS |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | VOLTS |
| Maximum average forward rectified current at $T_L=75^\circ\text{C}$ | $I_{(AV)}$ | 2.0 | | | | | | | Amps |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 60.0 | | | | | | | Amps |
| Maximum instantaneous forward voltage at 2.0A | V_F | 1.1 | | | | | | | Volts |
| Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$ | I_R | 5.0 50.0 | | | | | | | μA |
| Typical junction capacitance (NOTE 1) | C_J | 30.0 | | | | | | | pF |
| Typical thermal resistance (NOTE 2) | $R_{\theta JA}$ | 50.0 | | | | | | | $^\circ\text{C}/\text{W}$ |
| Operating junction and storage temperature range | T_J, T_{STG} | -50 to +150 | | | | | | | $^\circ\text{C}$ |

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES S2AF THRU S2MF

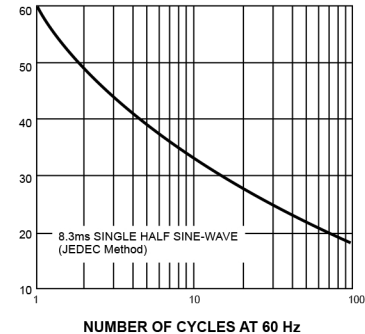
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



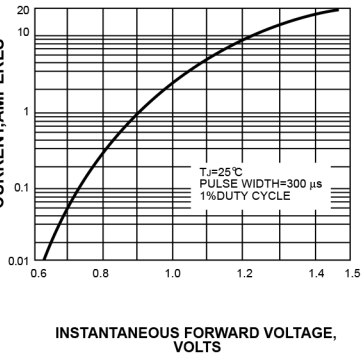
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



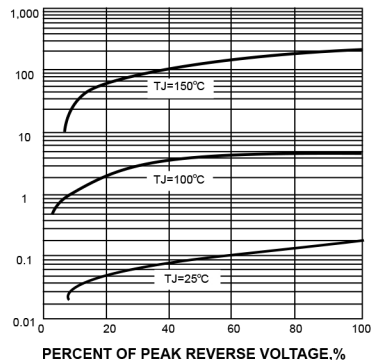
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



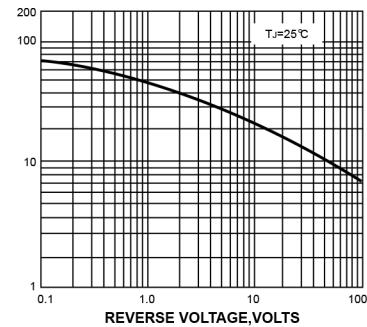
INSTANTANEOUS REVERSE CURRENT,
MICROAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



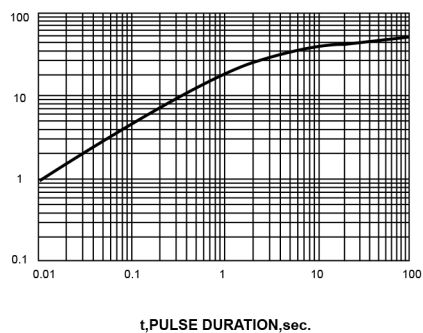
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



TRANSIENT THERMAL IMPEDANCE,
°C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



The cruce graph is for reference only, can't be the basis for judgment(曲线图仅供参考)!

单击下面可查看定价，库存，交付和生命周期等信息

[>>RCD\(达标电子\)](#)